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ABSTRACT

5 A substrate cutting apparatus for cutting a substrate
includes a scribe line forming means for forming a scribe
line on a substrate and a breaking means for breaking the
substrate along the scribe line. The breaking means includes
means for spraying a heated fluid having a temperature
sufficient to cause expansion of the substrate onto the scribe
line formed on the substrate so as to further extend a vertical
10 crack extending from the scribe line in the thickness
direction of the substrate.